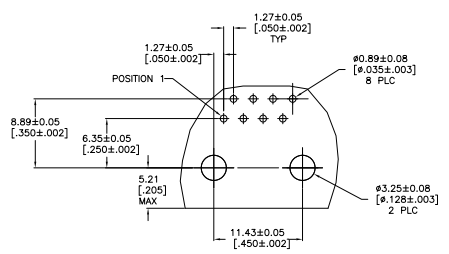
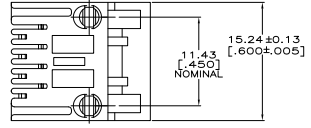
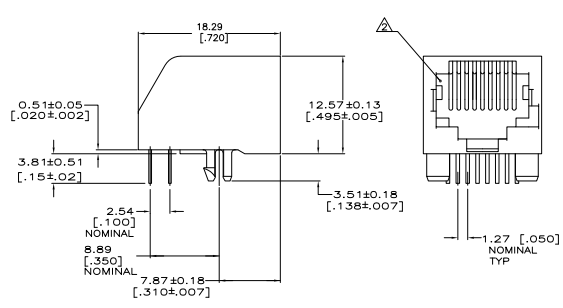


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REV	DATE	DESCRIPTION	BY	APP'D
AA	00			
B	02-07-2006			



RECOMMENDED PRINTED  
 CIRCUIT BOARD LAYOUT  
 COMPONENT SIDE

- MATERIAL: HOUSING – HTN MOLDING COMPOUND, UL 94V-0, COLOR: BLACK  
 TERMINAL – 0.36[.014] THICK PHOS BRONZE PLATED WITH 1.27μm[.000050] MINIMUM THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81μm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27μm[.000050] MINIMUM THICK NICKEL UNDERPLATE.
- CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- BULK PACKAGED IN A TRAY

5569118-1  
 PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DESIGNED BY: J. FERNANDEZ	DESIGNED BY: J. WESTMAN	DATE: 108-1163	REVISED BY: R. FLUENDER	REVISED BY: R. FLUENDER	DATE: 114-2048	DATE: 100779	DATE: 05569118	DATE: 4-1	DATE: 1	DATE: 1	DATE: B
UNLESS OTHERWISE SPECIFIED:	UNLESS OTHERWISE SPECIFIED:	UNLESS OTHERWISE SPECIFIED:	UNLESS OTHERWISE SPECIFIED:	UNLESS OTHERWISE SPECIFIED:	UNLESS OTHERWISE SPECIFIED:	UNLESS OTHERWISE SPECIFIED:	UNLESS OTHERWISE SPECIFIED:	UNLESS OTHERWISE SPECIFIED:	UNLESS OTHERWISE SPECIFIED:	UNLESS OTHERWISE SPECIFIED:	UNLESS OTHERWISE SPECIFIED:	UNLESS OTHERWISE SPECIFIED:	UNLESS OTHERWISE SPECIFIED:
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